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U.S. Patent Application No. 09/503,170
Attorney Docket No. 4329.2230

PROPOSED AMENDMENTS TO CLAIMS

1. (Currently Amended) A resin encapsulating apparatus for forming a resin sealing body on a semiconductor chip mounted on a carrier comprising:

a retaining section which retains the carrier on which the semiconductor chip is mounted;

a mask set on the carrier and having an opening at which a part of the semiconductor chip is exposed;

an extruding section configured to extrude a fluidizing resin in an extruding direction into the opening of the mask;

a first drive section which drives the extruding section;

a squeegee which causes a movement of the fluidizing resin present over the opening which is extruded from the extruding section into the opening, an interval between the extruding section and the squeegee being set to be wider than a length of the opening in the extruding direction; and

a second drive section which drives the squeegee independently of the first drive section which drives the extruding section.

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8. (Currently Amended) A resin encapsulating apparatus for forming a protective resin sealing body on a semiconductor chip mounted on a carrier in which the resin sealing body and external connection balls are formed on the same surface side of the semiconductor chip, the resin encapsulating apparatus comprising:

a retaining section which retains the carrier on which the semiconductor chip is mounted;

a mask set on the carrier and having an opening at which, when the mask is set on the carrier, an area of the semiconductor chip at which the resin sealing body is to be formed is exposed;

an extruding section configured to extrude a fluidizing resin in an extruding direction into the opening of the mask;

a first drive section which drives the extruding section;

a squeegee which causes a movement of the fluidizing resin present over the opening which is extruded from the extruding section into the opening, an interval between the extruding section and the squeegee being set to be wider than a length of the opening in the extruding direction; and

a second drive section which drives the squeegee independently of the first drive section which drives the extruding section.

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27. (New) A resin encapsulating apparatus for forming a resin sealing body on a semiconductor chip mounted on a carrier comprising:

a retaining section which retains the carrier on which the semiconductor chip is mounted;

a mask set on the carrier and having an opening at which a part of the semiconductor chip is exposed;

an extruding section configured to extrude a fluidizing resin in an extruding direction into the opening of the mask;

a first drive section which drives the extruding section;

a squeegee which causes a movement of the fluidizing resin present over the opening which is extruded from the extruding section into the opening, an interval between the extruding section and the squeegee being set to be shorter than a length of the opening in the extruding direction; and

a second drive section which drives the squeegee independently of the first drive section which drives the extruding section.

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28. (New) A resin encapsulating apparatus for forming a protective resin sealing body on a semiconductor chip mounted on a carrier in which the resin sealing body and external connection balls are formed on the same surface side of the semiconductor chip, the resin encapsulating apparatus comprising:

a retaining section which retains the carrier on which the semiconductor chip is mounted;

a mask set on the carrier and having an opening at which, when the mask is set on the carrier, an area of the semiconductor chip at which the resin sealing body is to be formed is exposed;

an extruding section configured to extrude a fluidizing resin in an extruding direction into the opening of the mask;

a first drive section which drives the extruding section;

a squeegee which causes a movement of the fluidizing resin present over the opening which is extruded from the extruding section into the opening, an interval between the extruding section and the squeegee being set to be shorter than a length of the opening in the extruding direction; and

a second drive section which drives the squeegee independently of the first drive section which drives the extruding section.